

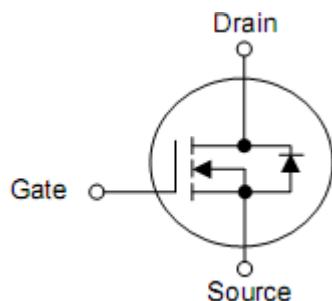
1. Features

- $R_{DS(ON)}=4.3\text{m}\Omega(\text{typ.}) @ V_{GS}=10\text{V}$, DFN3*3/DFN5*6
- $R_{DS(ON)}=4.5\text{m}\Omega(\text{typ.}) @ V_{GS}=10\text{V}$, TO-252
- Very Low On-resistance $R_{DS(ON)}$
- Low Crss
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

2. Applications

- PWM Application
- Power Management
- Load switch

3. Symbol



Pin		Function
DFN3*3/DFN5*6	TO-252	
4	1	Gate
5,6,7,8	2	Drain
1,2,3	3	Source

5. Ordering Information

Part Number	Package	Brand
KNG3403C	DFN3*3	KIA
KNY3403C	DFN5*6	KIA
KND3403C	TO-252	KIA

6. Absolute maximum ratings

$T_C=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Rating		Units
		DFN3*3 DFN5*6	TO-252	
Drain-source voltage	V_{DSS}	30		V
Continuous drain current	I_D	80		A
	I_D	45		A
Pulsed drain current -Pulsed ¹⁾	I_{DM}	320		A
Gate-source voltage	V_{GS}	± 20		V
Single pulse avalanche energy ²⁾	E_{AS}	306		mJ
Power dissipation ($T_C=25^\circ\text{C}$)	P_D	70	83	W
Operating junction and storage temperature range	T_J, T_{STG}	-55 to 150		°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	300		°C

*Drain current limited by maximum junction temperature.

7. Thermal characteristics

Parameter	Symbol	Rating		Unit
		DFN3*3/DFN5*6	TO-252	
Thermal resistance junction-case	$R_{\theta JC}$	1.8	1.5	°C/W

8. Electrical characteristics

($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units	
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V	
Drain-source leakage current	I_{DSS}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA	
Gate-source forward leakage	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA	
Gate threshold voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.6	2.2	V	
Drain-source on-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	DFN3*3 DFN5*6	-	4.3	6.0	$\text{m}\Omega$
			TO-252	-	4.5	6.0	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	DFN3*3 DFN5*6	-	6.7	9.2	$\text{m}\Omega$
			TO-252		7.5	9.2	$\text{m}\Omega$
Input capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}$ $f=1\text{MHz}$	-	1972	-	pF	
Output capacitance	C_{oss}		-	214	-	pF	
Reverse transfer capacitance	C_{rss}		-	176	-	pF	
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=15\text{V},$ $R_{\text{G}}=2.7\Omega, I_{\text{D}}=30\text{A}^3)$		21		ns	
Rise time	t_r			16		ns	
Turn-off delay time	$t_{\text{d}(\text{off})}$			62		ns	
Fall time	t_f			12		ns	
Total gate charge(10V)	Q_g	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=30\text{A}$ $V_{\text{GS}}=10\text{V}^3)$	-	37.2	-	nC	
Gate-source charge	Q_{gs}		-	5.7	-	nC	
Gate-drain charge	Q_{gd}		-	7.6	-	nC	
Maximum Continuous Drain-Source Diode Forward Current	I_s	—	-	-	80	A	
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}	—	-	-	320	A	
Diode forward voltage	V_{SD}	$I_{\text{SD}}=30\text{A}, V_{\text{GS}}=0\text{V},$ $T_J=25^\circ\text{C}$	-	-	1.2	V	
Reverse Recovery Time	t_{rr}	$I_F=80\text{A}, \text{di}/\text{dt}=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	-	32	-	nS	
Reverse Recovery Charge	Q_{rr}		-	12	-	nC	

Note:

- 1) Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- 2) EAS condition : $T_J=25^\circ\text{C}, V_{\text{DD}}=15\text{V}, V_G=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$
- 3) Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

9. Typical operating characteristics

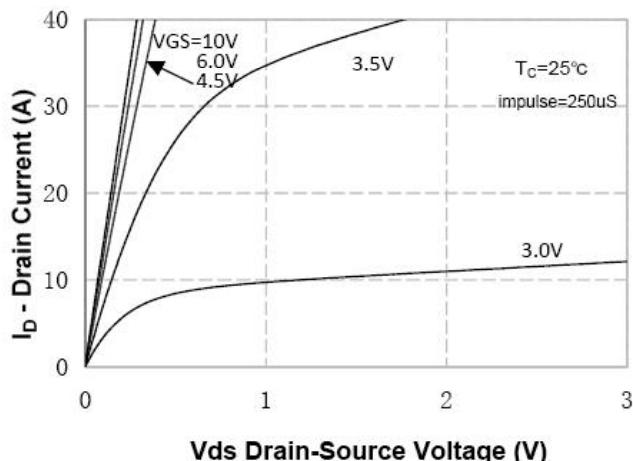


Figure 1. On-Region Characteristics

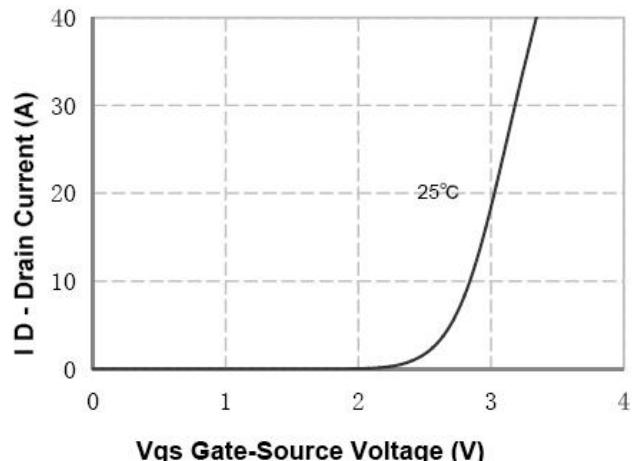


Figure 2. Transfer Characteristics

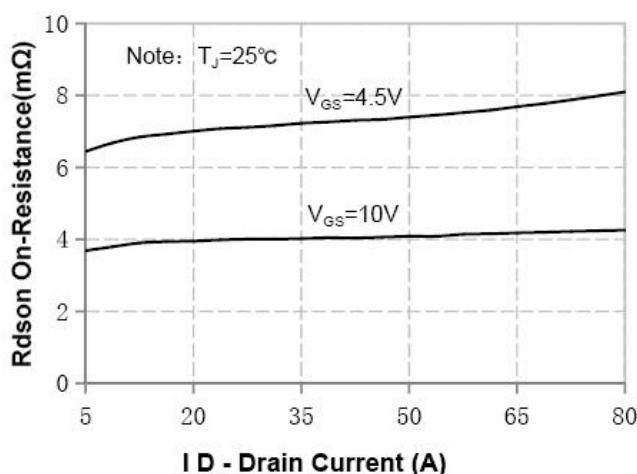


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

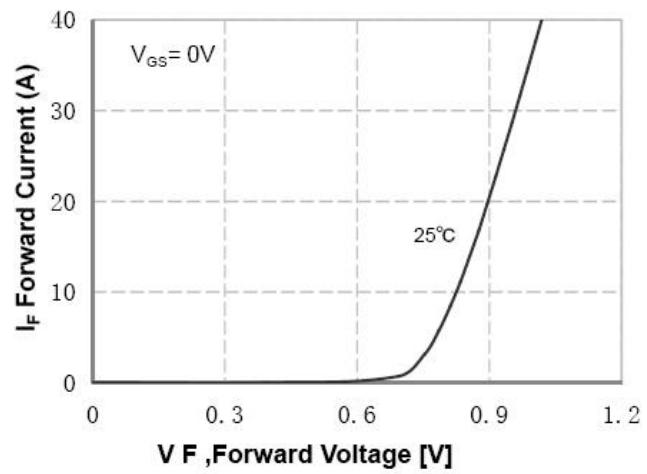


Figure 4. Body Diode Forward Voltage Variation vs. Source Current

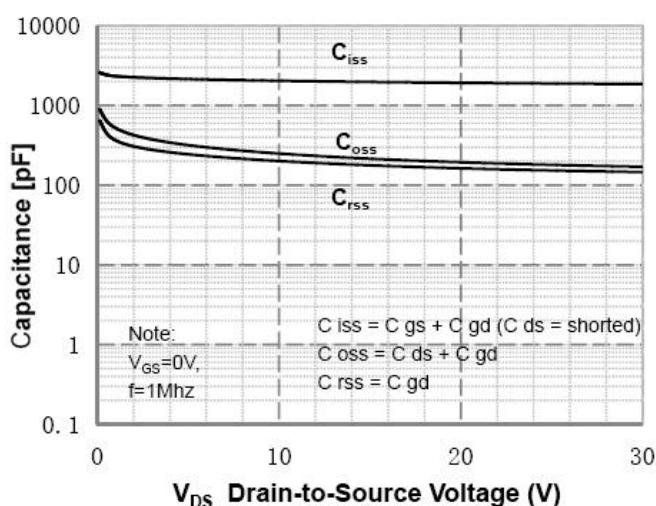


Figure 5. Capacitance Characteristics

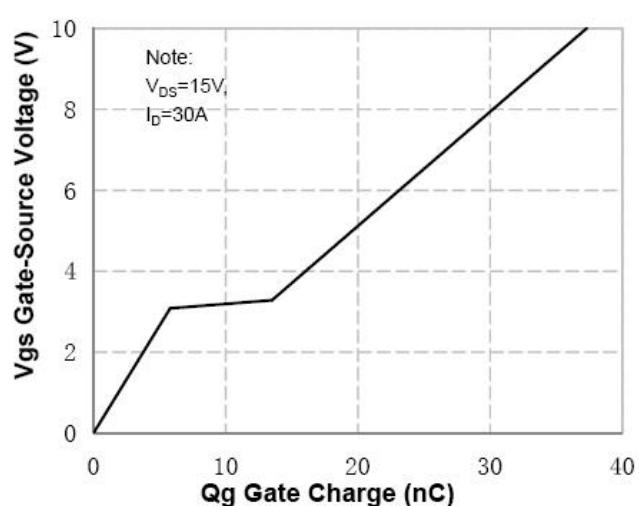


Figure 6. Gate Charge Characteristics

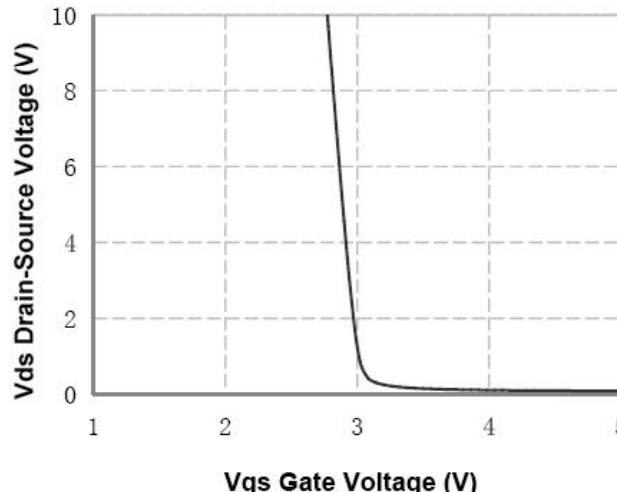


Figure 7. V_{ds} Drain-Source Voltage vs Gate Voltage

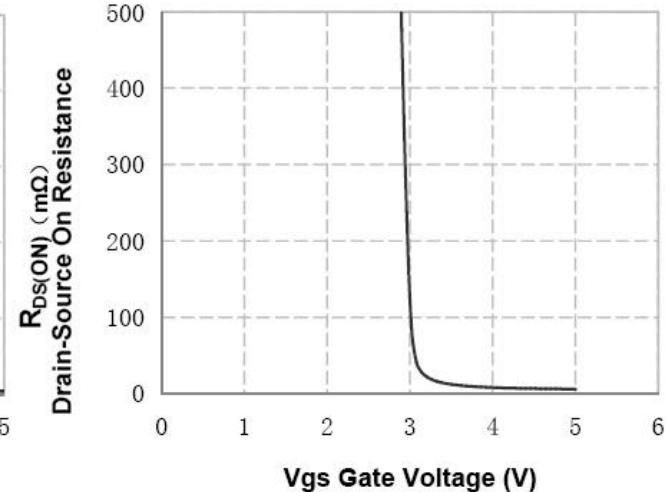


Figure 8. On-Resistance vs Gate Voltage

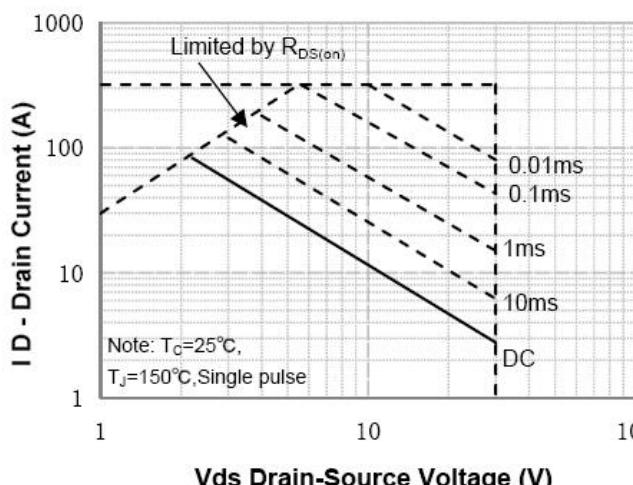


Figure 9. Maximum Safe Operating Area

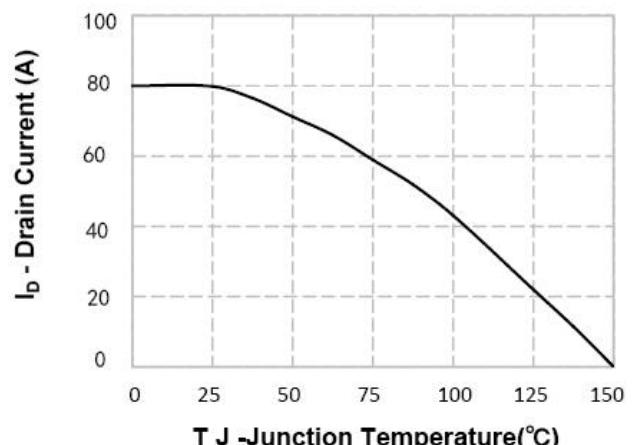


Figure 10. Maximum Continuous Drain Current vs Case Temperature

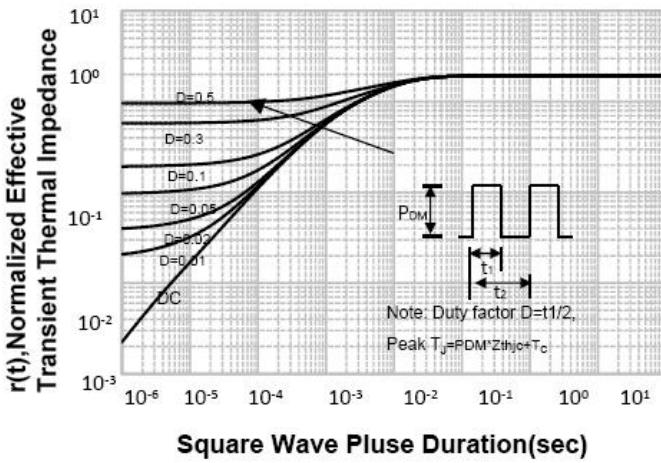
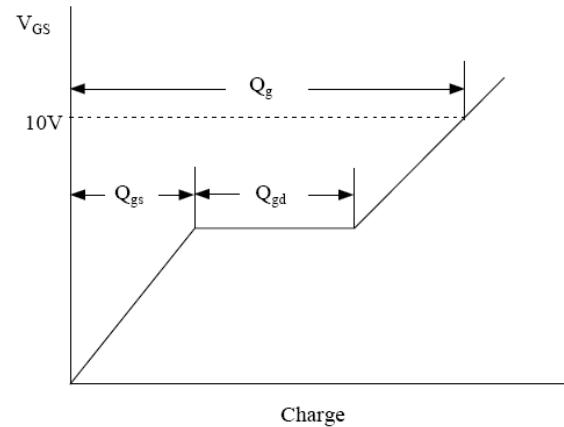
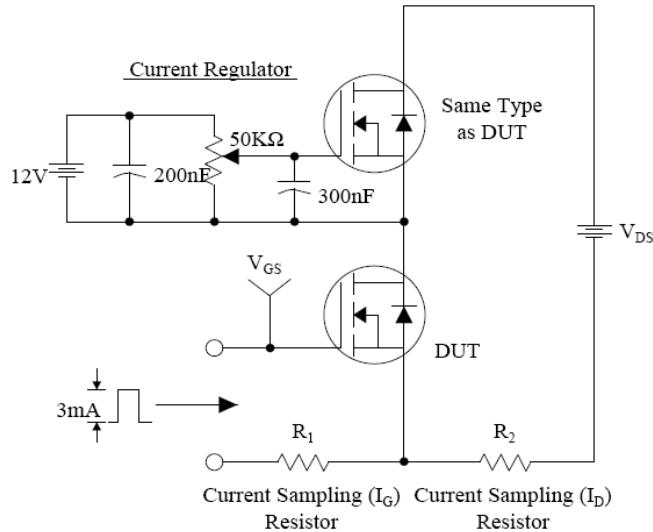


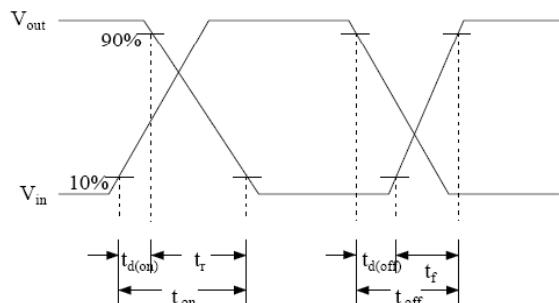
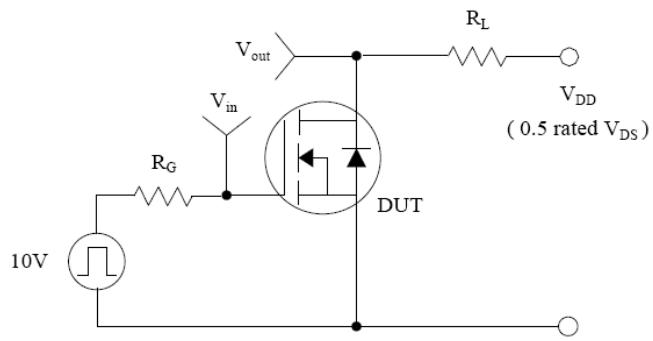
Figure 11. Transient Thermal Response Curve

10. Test Circuits and Waveforms

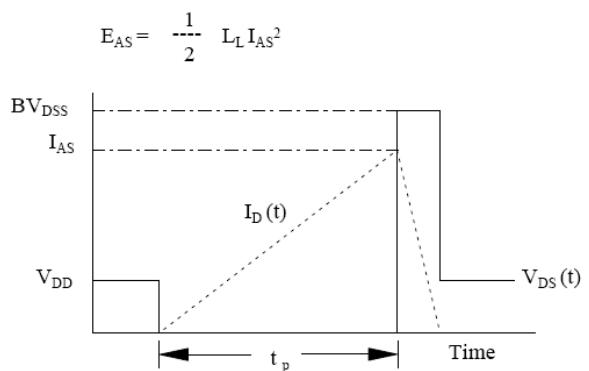
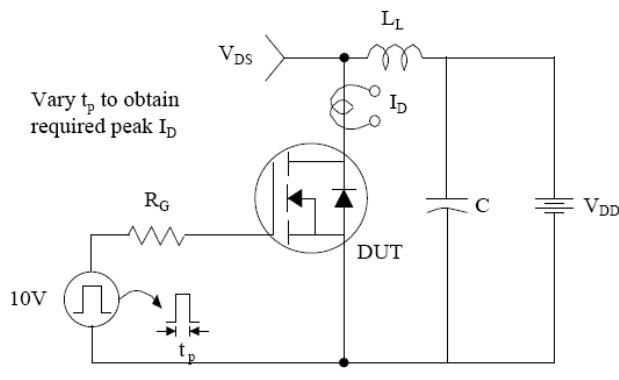
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

